



Krytek-300 Ion Source Conditioner

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Ideal Implanter Operation

Predictable:

High-availability with near-zero maintenance variability

Flexible:

Adapt quickly to synchronize scheduling of quals, PM's, Etc.

Agile:

Rapid lot-to-lot setup/changeover

Ultra Clean:

Minimize Particles and Cross Contamination

Low Cost:

Excellent OEE performance to minimize tool count



Krytek-300 Attributes

- The Krytek-300 is an Ion Implant Productivity Improvement Tool
- Typically one hour shorter source exchange time when everything occurs as expected and the implanter returns to operation smoothly
- Removes contaminants from the surfaces of the source prior to exposure in the implanter
- Minimizes the risk of extended downtime events due to infant mortality
- Improves predictability and reduces variability for overall wafer fab performance



Krytek-300 Features

- Automated test and condition sequence
- Automated vacuum and cooling water leak testing
- Electrical pre-testing Arc voltage, filament, TC, etc...
- Pre-out gassing of filament and arc chamber
- Arsenic oxide, Indium Chloride burn-off
- Vacuum storage of conditioned sources ready to use
- Designed to process sources and components from all the major Implant OEM's



Krytek-300 Conditioner Process

Process

- Install source.
- 2. Start automated recipe.
- 3. Source pumps down to set point.
- 4. Leak check.
- 5. Thermo-couples and water flow tested.
- 6. Filament ramp (pressure monitored for over pressure and adjust ramp).
- 7. Arc check (checks for short in filament to arc chamber at temperature).
- 8. Vaporizer test.

Vaporizer short/ open test.

Vaporizer ramp and hold at temperature.

Vaporizer heater test (voltage Vs Current at temperature).

- 9. Cool down vaporizer (quick cool if applicable).
- 10. Cool down filament.
- 11. Print and save report.
- 12. Shut down and vent of manifold.
- 13. System ready for next source.

Computer

- Industrial PC
- Windows XP Platform
- Krytek 300 Software
- Inficon Tware lite (RGA)
- Varian Turbo-V 301 SW

Software

- Recipe-driven automated testing and conditioning sequence
- Record of test stored to industrial PC for easy export and printing
- Rapid fault identification
- Automated and manual leak checking



Krytek 300 Systems

Vacuum System

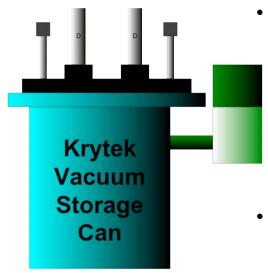
- Standard pumping system
- Varian 300 dry scroll pump
- Varian Turbo-V 301 Navigator
- Inficon RGA
- Pfeiffer full range pressure gauge
- Varian pneumatic valving

Power Supplies

- XANTREX Filament Power Supply (2.5KW) Optional (10V,250 amp or 20V 125 amp)
- XANTREX Emission Power Supply (1 KW) 600 Volt 1.6 Amps
- XANTREX Vaporizer Power Supply (1 KW) 100 Volt 10 Amp
- Arc Power Supply 1.7 KV, 1.3 mA



Krytek Storage:



Source Stored under Vacuum after Conditioning

No Moisture Added

No Oxide Formation

No Added Particulates

Minimal Implanter Conditioning Needed

Ready to Operate at Short Notice





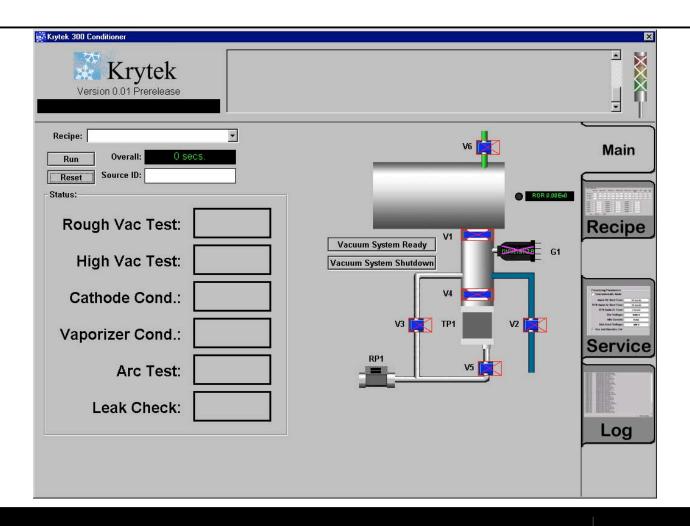
The Krytek 300 - Operation

- The Krytek-300 is completely automated and minimizes the need for technician intervention
- The Krytek-300 is preprogrammed for reproducibility with specific recipes for each source model



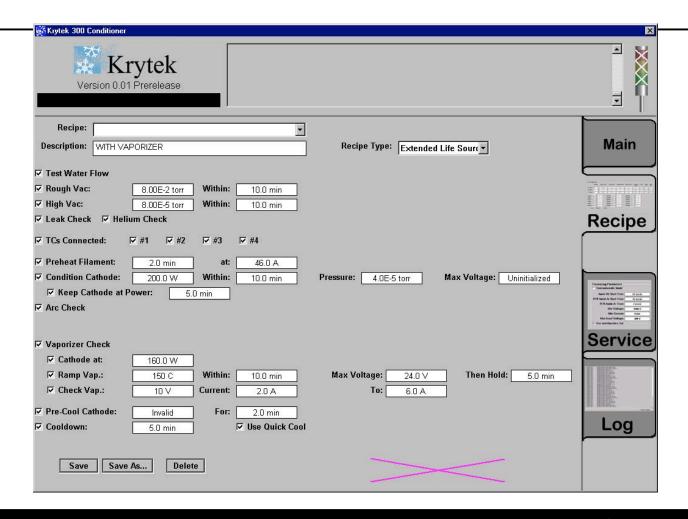


Main Page



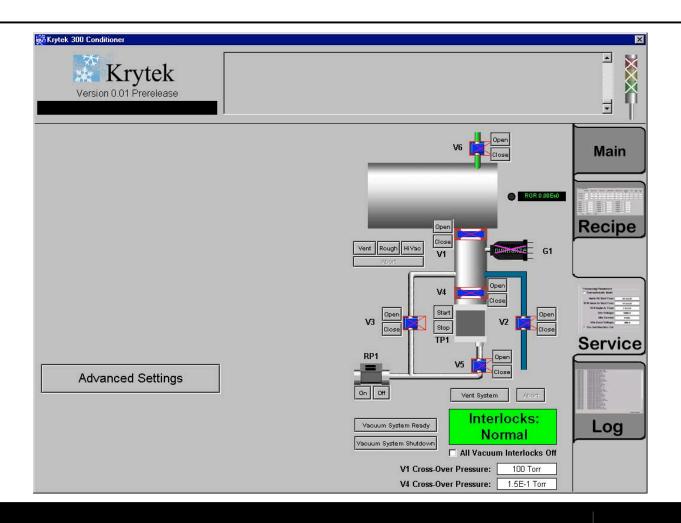


Recipe Page



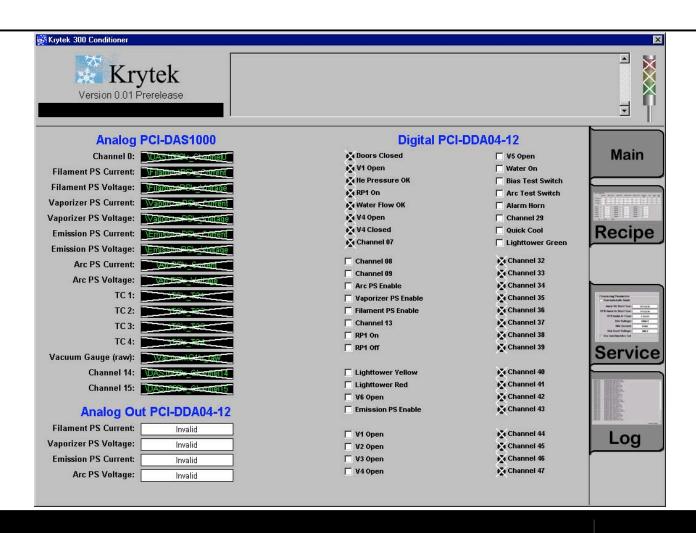


Service Page





Raw Input / Output Page





Summary

- Source Integrity and Out-gassing are the most important benefits of the Krytek.
 - There are often differences in source operation depending on the individual doing the rebuild.
 - Time is saved by replacing otherwise needed "in-situ" out-gassing and prevention of early or immediate failure of the source
 - The Krytek performs a quality control function for key parameters assuring improved repeatability of source operation.
- **Beam Purity**: Source cleaning materials leave long lasting residues in the arc chamber and other regions of the source. Unwanted materials include:
 - Various types of Scotch-brite and unapproved solvents
 - Bead-blast materials and residues especially Sodium from blast beads
 - ... these can generate unwanted ions and unwanted molecular species. Disassociated ions can appear in the beam or close to the beam.
- Finally if a modern implanter with Auto-tuning has instability on source start-up it often can't be handled by the computer.